



EPEPS is the premier international conference on advanced and emerging issues in the electrical modeling, analysis, and design of electronic interconnections, packages, and systems. Over four days, the conference will feature the latest advancements in modeling, design, and measurement techniques for SI, PI, and performance optimization in high-speed, RF, wireless and quantum systems.

EPEPS 2026 will be held in Fort Worth, Texas. We look forward to seeing you in Texas!

Xu Chen & Rajen Murugan

Call for papers

We welcome new and unpublished contributions on:

Interconnects design & technologies

- High-speed channels, backplanes, SerDes, memory, DDR interfaces
- Interconnect and transceiver co-design, equalization
- Signal & power integrity issues
- Jitter, noise
- High-frequency interconnects, packages, antennas-in-package
- Novel/unconventional interconnect technologies

Manufacturing and measurement

- Manufacturing, testing, reliability
- Measurement techniques

Packaging and integration

- Advanced packaging, 3D integration
- Heterogeneous integration
- Design of interconnects and packages
- Quantum systems: interconnection & packaging aspects

Modeling and simulation

- Modeling, simulation, computer-aided design
- Thermal, mechanical, multiphysics modeling
- ML and AI-based approaches to interconnect and packaging problems

General chair

Xu Chen

*University of Illinois
Urbana-Champaign*

Co-chair

Rajen Murugan

Texas Instruments

Awards & grants

- Best paper award
- Best student paper award
- Best poster paper award
- Best benchmark paper award
- Student travel grants

Important dates

Paper submission:

June 29, 2026

Acceptance:

End of July, 2026

Sponsor registration:

September 1, 2026

Early bird

registration:

September 1, 2026

